

## GaAs FET

### Recommended Soldering Flux and Cleaning Conditions

Low Noise GaAs FET K2 and K3 packages are cap molded epoxy resin but are not hermetically sealed.

Do not conduct flux cleaning after mounting, as it could cause degradation of electrical characteristics.

Use only non-cleaning flux solder paste for device mounting.

The following are the recommended non-clearing flux conditions.

Recommended non-cleaning flux

- Super low residue flux (ULF-500VS, ULF-210R)
- Low residue flux (CF-220V)
- Deactivation flux(AM-173)
- 0.2% (wt) or less chlorine content flux

Precautions:

Flux is generally divided into two types, rosin flux and aqueous flux.

Rosin flux is largely divided into three types, R, RMA, and RA, by order of activation.

- R type(Rosin base): non-active rosin flux, non-corrosive
- RMA type (Mildly Activated Rosin base): mildly activated rosin flux, non-corrosive, better solderability than R.
- RA type (Activated Rosin base): strongly activated rosin flux, better solderability than R, RMA but with strong corrosion behavior.

Aqueous flux is generally highly chlorinated and may cause degradation of the device.

Avoid high temperature and high humidity, even after using rosin flux, as solder residue may cause corrosion or insulation degradation of package pin or print circuit board.

Dirt and stains tend to adhere and may cause malfunctions. Therefore, take precautions to avoid this during cleaning.